


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	AMS/19/11885	
1.3 Title of PCI	Optimization of TEG structures positioning, in scribe lines of asic die, for LSM6DSO- products family.	
1.4 Product Category	LSM6DSO- products family	
1.5 Issue date	2019-12-06	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	FRANCKE CHRISTIANE
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2.2 Change responsibility	
2.2.1 Product Manager	Andrea Mario ONETTI
2.1.2 Marketing Manager	Simone FERRI
2.1.3 Quality Manager	Michele CALDERONI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Wafer Fab (Process)	Mask Frame : introduction of new structure or never tested structure, change of die scribe separation or scribe line width	ST France

4. Description of change

	Old	New
4.1 Description	Current TEG positioning in scribe lines (current Die Area)	New TEG positioning arrangement in scribe lines (unchanged Die area)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	The change is implemented for continuous improvement in assy process.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Dedicated FGs
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7. Timing / schedule

7.1 Date of qualification results	2020-02-03
7.2 Intended start of delivery	2020-03-09
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

11885 Public product.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
2980917	LSM6DSOTR	
3011638	LSM6DSOXTR	

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